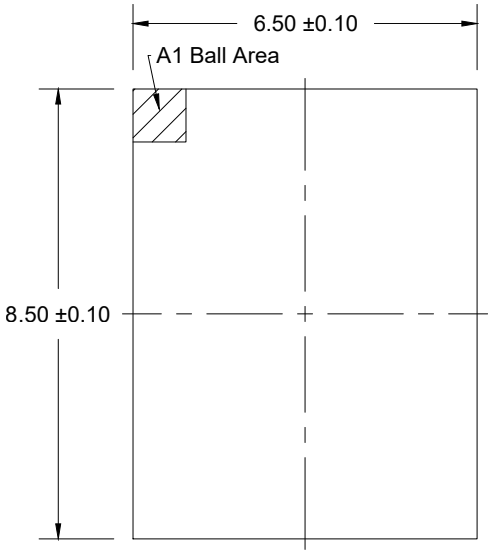
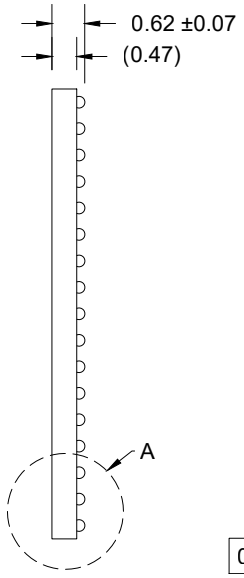
Package Outline Drawing

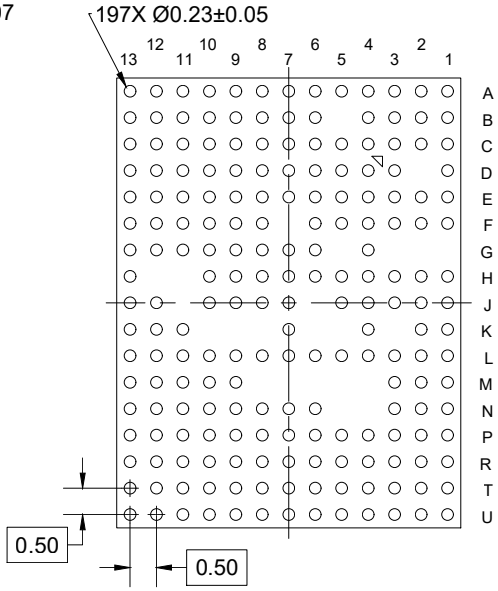
Package Code: AVR197D1
197-FCCSP (FCBGA) 6.50 x 8.50 x 0.62 mm Body, 0.50mm Pitch
PSC-4952-01, Revision: 00, Date Created: Apr. 21, 2022



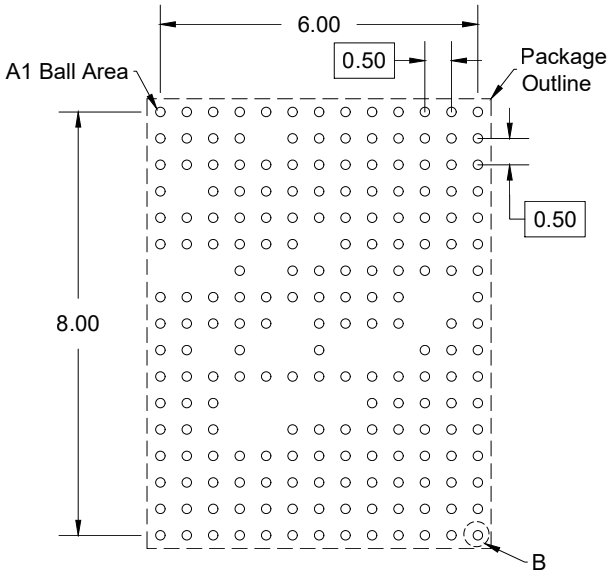
TOP VIEW



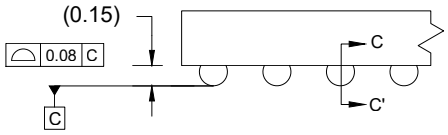
SIDE VIEW



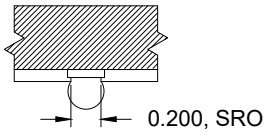
BOTTOM VIEW



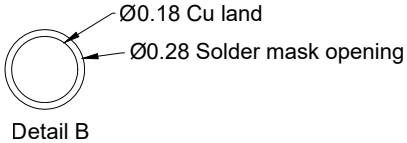
RECOMMENDED LAND PATTERN
(PCB Top View, NSMD Design)



Detail A
(Rotated 90° CW)



Section C-C'



Detail B

NOTES:

1. JEDEC compatible.
2. All dimensions are in mm and angles are in degrees.
3. Use ±0.05 mm for the non-toleranced dimensions.
4. Numbers in ( ) are for references only.
5. Pre-reflow solderball diameter is Ø0.22 mm.

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